

TE Internal #: 2291634-2

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, Internal/External EMI Springs, SFP+, Not Optional, 1 x 1, Through

Hole - Press-Fit, 1 Port

View on TE.com >

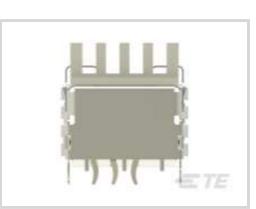


Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+











Pluggable I/O Product Type: Cage Assembly

Data Rate (Max): 16 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: **SFP+** Lightpipe Options: **Not Optional**

Features

Product Type Features

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nal
Board
rcuit Board
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16 Gb/s

Data Rate (Max)



Heat Sink Height Class	SAN
Heat Sink Height	6.5 mm[.255 in]
Heat Sink Style	Fin
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Cage Material	Copper Alloy
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-65 – 221 °F]
Operation/Application	
Heat Sink Compatible	Yes
For Use With Pluggable I/O Products	SFP+ SMT Connector
Pluggable I/O Applications	SFP+
Circuit Application	Signal
Packaging Features	
Packaging Method	Tray
Other	

Product Compliance

EMI Containment Feature Type

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Internal/External EMI Springs



Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





26 AWG









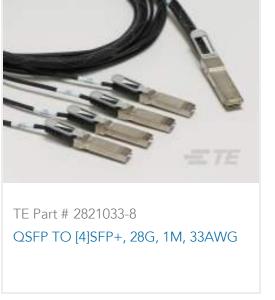










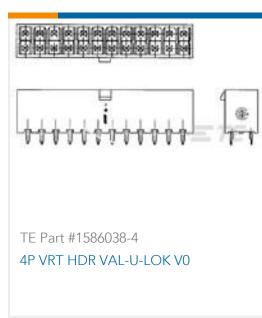


Customers Also Bought





















Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2291634-2_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2291634-2_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2291634-2_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

Product Environmental Compliance

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, Internal/External EMI Springs, SFP+, Not Optional, 1 x 1, Through Hole - Press-Fit, 1 Port



Product Compliance

English

Product Compliance

English